

# E-1800 R6 (4x3.5"+4x2.5")

High-Reliability, Medium-Density Enterprise Computing Systems



UNICOM Engineering's next generation E-Series platforms are built on 3rd Gen Intel® Xeon® Scalable processors with support for the latest Intel Optane persistent memory, network adapters, and storage. The E-1800 R6 enterprise computing system delivers the industry's best combination of high performance, reliability, and flexibility to match medium-density storage and I/O requirements and is optimized for a variety of cloud, AI, security, scale out and HPC workloads. This system's unique design featuring HDD and SSD support offers high value, scale out hybrid storage to meet a variety of application needs in a single platform.

### Features and Benefits

#### **Built for Performance**

- Supports up to two Intel Ice Lake-SP Microarchitecture processor for maximum performance and density
- Supports up to 32 DDR4-3200 MT/s ECC DIMMs across 16 channels for faster application execution and greater overall stability
- Supports up to 16 Intel Optane DC Persistent Memory Modules of up to 512GB each for even greater application performance
- Supports up to 4 x 3.5" hot swap HDDs and 4 x 2.5" 7mm hot swap SSDs to provide high density, low cost hybrid storage options
- PCle Gen4 provides support for the latest generation of network, accelerator, and RAID controllers

#### **Built for High-Reliability Applications**

- Enterprise class drives and RAID ensure maximum reliability
- Hot swap hard drives and power supplies ensure low Mean-Time-To-Repair (MTTR)
- Redundant hot swap power supplies ensure high reliability in case of a failure

#### Gain a Competitive Advantage

Many times the best way to deliver a truly competitive solution is to leverage the products, skills, and resources of proven partners. Building on innovative Intel technology, UNICOM Engineering's design, integration, logistics and support expertise helps customers streamline software application deployment and shorten time to revenue. Our strong foundation of engineering expertise, process-driven manufacturing, technology partner relationships, and an unrelenting commitment to quality has made UNICOM Engineering one of the most trusted deployment partners in the industry.



## E-1800 R6 (4x3.5"+4x2.5")

## technical specifications



E-1800 R6 Rear View

#### Form Factor

1U rack mount

#### Dimensions (HxWxD)

1.70" (43.2mm) x 17.2" (438mm) x 32.6" (828mm)

#### **Processor Support**

- Support for one or two Intel Xeon Ice Lake-SP CPUs
- Dual SocketP-4 LGA4189
- Maximum supported Thermal Design Power (TDP) of up to 270W

#### Chipset

Intel C621A chipset

#### Memory

- 32 DIMMs slots, 16 DIMM slots per processor
- 8 memory channels per processor, 2 DIMMs per channel per processor
- DDR4-3200 MT/s ECC Registered
- Intel Optane Persistence Memory Series 200

#### **Storage Bay Options**

- 4 x 3.5" SAS/SATA/NVMe hot swap drive bays
- 4 x 2.5" SAS/SATA/NVMe hot swap SSD (7mm) drive bays
- 2 x M.2 NVMe/SATA connectors

#### **Storage Options**

- 3.5" SAS/SATA HDD, 12 Gb/s/6 Gb/s
- 2.5" SATA SSD, 6 Gb/s
- 2.5" NVMe SSD, U2
- 7mm SATA/NVMe SSD
- M.2 SATA/NVMe SSD

#### **Integrated RAID Support**

- On-Board SATA Software RAID levels 0/1/5/10
- Optional Intel Virtual RAID on CPU (VROC) for NVMe with activation key

#### **OCP Module Slot**

- 1 Intel OCP 3.0 Expansion Module slot to support an optional module
- 10 GbE SFP+, 25 GbE SFP28, 50 GbE SFP28, 100 GbE QSFP28 NICs

#### Riser Cards

- Support for 3 riser card slots, Max 3 PCle addin card
- Riser Slot #1: 1 x PCle Gen4 x16 @ x16 lanes LP/HL
- Riser Slot #2: 1 x PCle Gen4 x16 @ x16 lanes LP/HL
- Interposer Riser Slot: 1 x PCle Gen4 x8 @ x8 lanes
  I P/HI

#### PCIe Cards and Add-in Options

- 1 GbE, 10 GbE, 25 GbE 50 GbE, 100 GbE NICs, copper, fiber
- Entry / Enterprise RAID Controllers
- 16 Gb fibre channel

#### External I/O

- 1 video ports (DB-15) 1 rear
- 4 USB 3.0 ports 3 rear, 1 front
- 1 USB 2.0 port front
- 1 RJ-45 serial port rear
- 1 dedicated RJ-45 server management port rear

#### Server Management

- Integrated Baseboard Management Controller (BMC), IPMI 2.0 compliant
- Intel Remote Management Module 4 Management NIC for dedicated network interface

#### Security

Optional Intel Trusted Platform Module (TPM)

#### **Front Control Panel**

- System ID button with integrated LED
- Non-Maskable Interrupt (NMI) button
- Drive activity LEDs
- System cold reset button
- System status LED
- Power / sleep button with integrated LED

#### System Fans

- 8 hot swap system fans
- 1 power supply fan for each power supply module

#### **Power Supply Options**

- Up to 2 hot swap redundant capable power supply
- 1300W AC Titanium, 1600W AC Titanium

#### **OS Support**

- Microsoft Windows Server 2019 / 2016
- Red Hat Enterprise Linux 8.2 / 7.8
- SuSE Enterprise Linux 15 sp2
- Ubuntu Linux 20.04-LTS
- VMWare ESXi 7.0 / 6.7 Update 3
- CentOS 8.2

#### Regulatory Approval

- National Recognized Testing Laboratory (NRTL), Conforming European (CE) Mark / Safety, Certification Body (CB)
- Federal Communications Commission (FCC)
  Parts 15 Class A, Voluntary Control Council for Interference (VCCI), Australia & New Zealand Regulatory Compliance Mark (RCM)
- Restriction of the use of certain Hazardous Substances (RoHS) Compliant

#### **Environment**

- Operating temperature: 10°C to 35°C (50 to 95°F)
- Non-operating temperature: -40°C to 70°C (-40 to 158°F)
- Non-operating humidity: 90%, non-condensing at 28°C (82°F)

#### Warranty

- Standard two-year limited warranty, return to factory.
- Optional extended warranty and advance replacement service.

#### Support and Maintenance Services

UNICOM Engineering offers a variety of support and maintenance service programs to ensure high availability, rapid response, effective troubleshooting, fast parts replacement and 24-hour support.

Please visit www.unicomengineering.com/supportservices for more information.



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